DESCRIPTION

The SPN3055 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, such as DC/DC converter and Desktop computer power management.

The package is universally preferred for commercial industrial surface mount applications

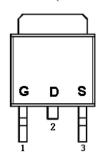
APPLICATIONS

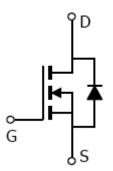
- Power Management in Desktop Computer
- DC/DC Converter
- LCD Display inverter

FEATURES

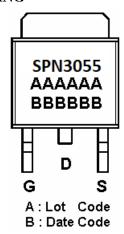
- 30V/12A,RDS(ON)= $60m\Omega$ @VGS=10V
- 30V/6A,RDS(ON)= $90m\Omega$ @VGS=4.5V
- Super high density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- ◆ TO-252-2L package design

PIN CONFIGURATION (TO-252-2L)





PART MARKING



PIN DESCRIPTION						
Pin	Symbol	Description				
1	G	Gate				
2	D	Drain				
3	S	Source				

ORDERING INFORMATION

Part Number	Package	Part Marking		
SPN3055T252RGB	TO-252-2L	SPN3055		

[※] SPN3055T252RGB : Tape Reel ; Pb − Free ; Halogen - Free

ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

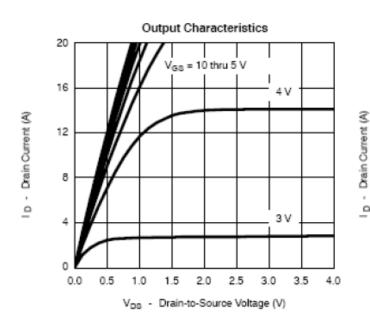
Parameter		Symbol	Typical	Unit
Drain-Source Voltage		Vdss	30	V
Gate –Source Voltage		VGSS	±20	V
Continuous Drain Current(T _J =150°C)	TA=25°C TA=70°C	- ID	12 8	A
Pulsed Drain Current		Ірм	20	A
Continuous Source Current(Diode Conduction)		Is	12	A
Power Dissipation	TA=25°C TA=70°C	PD	40 20	W
Avalanche Energy with Single Pulse ($Tj=25^{\circ}C$, $L=0.14mH$, $Ias=10A$, $VD=20V$.)		E _{AS}	7	mJ
Operating Junction Temperature		TJ	-55/175	°C
Storage Temperature Range		Tstg	-55/175	°C
Thermal Resistance-Junction to Ambient		RθJA	100	°C/W

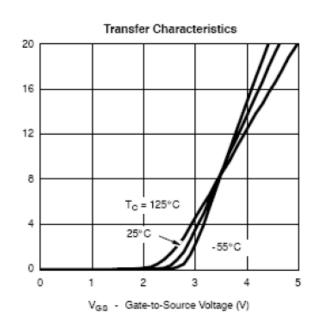
ELECTRICAL CHARACTERISTICS

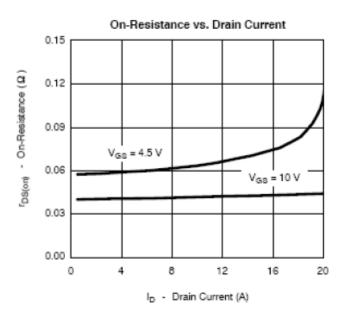
(TA=25°C Unless otherwise noted)

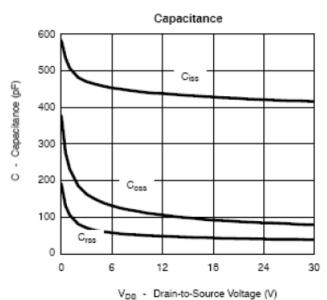
Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static	L	1	L	•	ı		
Drain-Source Breakdown Voltage	V(BR)DSS	Vgs=0V,ID=-250uA	30			17	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=-250uA	1.0		3.0	V	
Gate Leakage Current	Igss	VDS=0V,VGS=±20V			±100	nA	
Zero Gate Voltage Drain Current	IDSS	VDS=24V,VGS=0V VDS=24V,VGS=0V TJ=55°C			1 10	uA	
Drain-Source On-Resistance	RDS(on)	VGS=10V,ID=12A VGS=4.5V,ID=6A		0.050 0.067	0.060 0.090	Ω	
Forward Transconductance	gfs	VDS=10V,ID=12A		20		S	
Diode Forward Voltage	Vsd	Is=6A,VGS=0V		1.0	1.2	V	
Dynamic							
Total Gate Charge	Qg	V _{DS} =15V,V _{GS} =10V -I _D =12A		4.5	10	nC	
Gate-Source Charge	Qgs			0.8			
Gate-Drain Charge	Qgd	-ID-12A		1.0			
Input Capacitance	Ciss	V _{DS} =15V,V _{GS} =0V f=1MHz		240		pF	
Output Capacitance	Coss			110			
Reverse Transfer Capacitance	Crss			17			
Turn-On Time	td(on)	V _{DD} =15V,R _L =15Ω		8	20	nS	
	tr			12	30		
Turn-Off Time	td(off)	ID=1.0A,VGEN=10V RG=6 Ω		17	35		
	tf			8	20		

TYPICAL CHARACTERISTICS

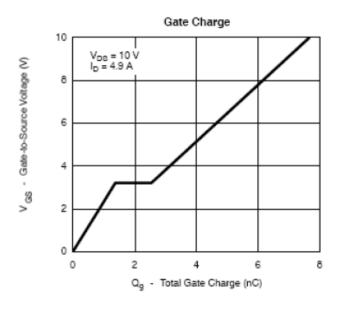


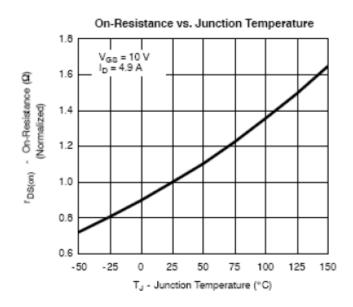


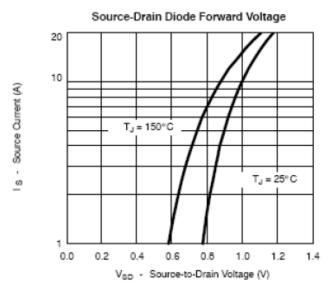


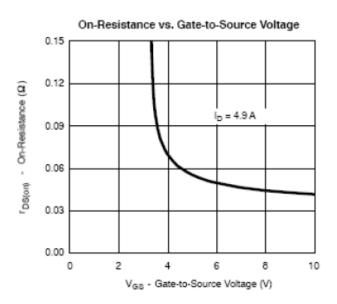


TYPICAL CHARACTERISTICS

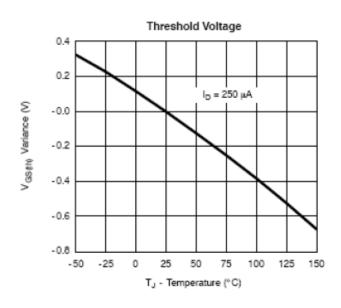


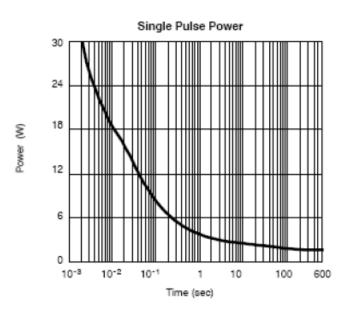


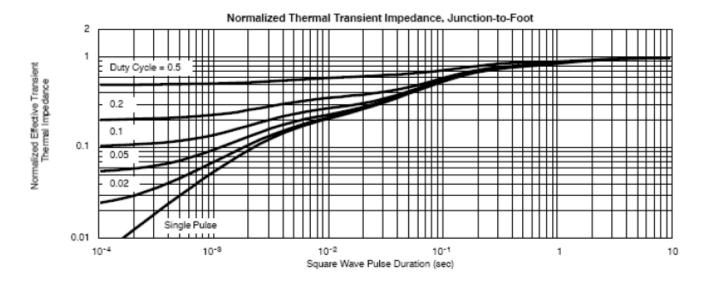




TYPICAL CHARACTERISTICS







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